

Features

- Provides ESD Protection per IEC 61000-4-2 Standard:
Air ±20kV, Contact ±15kV
- 1 Channel of ESD Protection
- High Peak Pulse Current per IEC 61000-4-5 Standard
- Typically Used in Cellular Handsets, Portable Electronics, Communication Systems, Computers and Peripherals
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: X1-DFN1006-2
- Low Profile Package (0.53mm max) and Ultra-small PCB Footprint Area (1.08 x 0.68mm max) Suitable for Compact Portable Electronics
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.001 grams (approximate)

X1-DFN1006-2



Bottom View



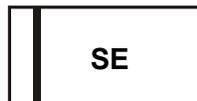
Device Schematic

Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
D18V0L1B2LP-7B	AEC-Q101	SE	7	8	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



SE = Product Type Marking Code
Line Denotes Pin 1

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	68	W	8/20μs, Per Figure 3
Peak Pulse Current	I _{PP}	2.0	A	8/20μs, Per Figure 3
ESD Protection – Contact Discharge	V _{ESD_Contact}	±15	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V _{ESD_Air}	±20	kV	IEC 61000-4-2 Standard

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	500	$^{\circ}\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^{\circ}\text{C}$

Electrical Characteristics (@ $T_A = +25^{\circ}\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V_{RWM}	—	—	18	V	—
Channel Leakage Current (Note 6)	I_{RM}	—	—	100	nA	$V_{RWM} = 18\text{V}$
Clamping Voltage, Positive Transients	V_{CL}	—	27	30	V	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{S}$
		—	30	34	V	$I_{PP} = 2\text{A}, t_p = 8/20\mu\text{S}$
Breakdown Voltage	V_{BR}	21	—	25	V	$I_R = 1\text{mA}$
Differential Resistance	R_{DIF}	—	2.2	—	Ω	$I_R = 1\text{A}, t_p = 8/20\mu\text{S}$
Channel Input Capacitance	C_T	—	7.0	12	pF	$V_R = 0\text{V}, f = 1\text{MHz}$

- Notes:
5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
 6. Short duration pulse test used to minimize self-heating effect.

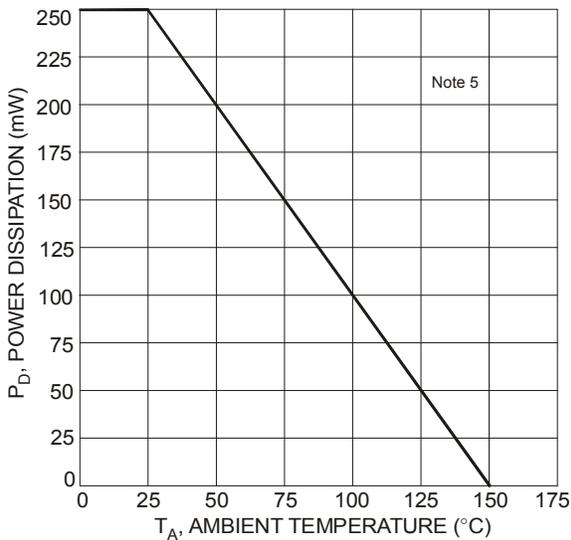


Figure 1 Power Derating Curve

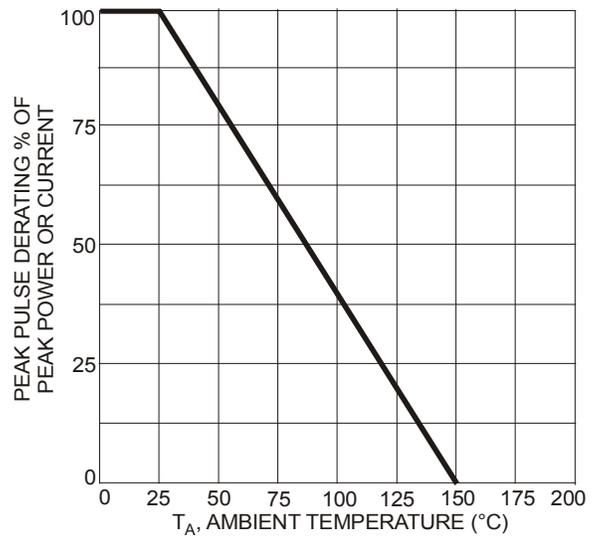


Figure 2 Pulse Derating Curve

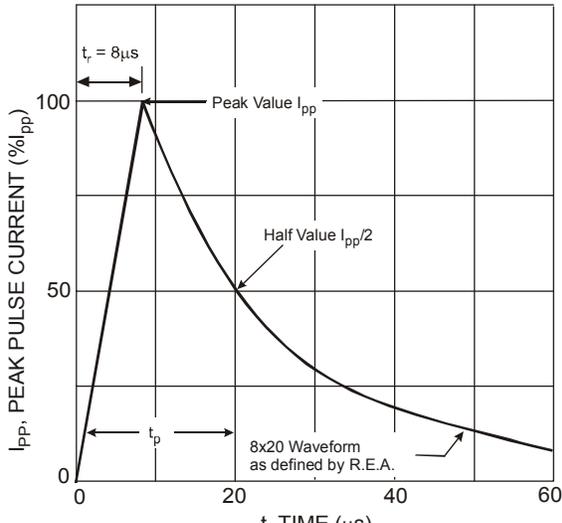


Figure 3 Pulse Waveform

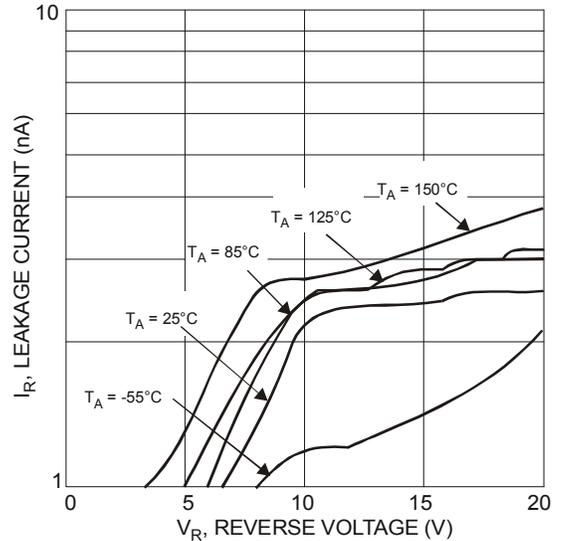


Figure 4 Typical Reverse Characteristics

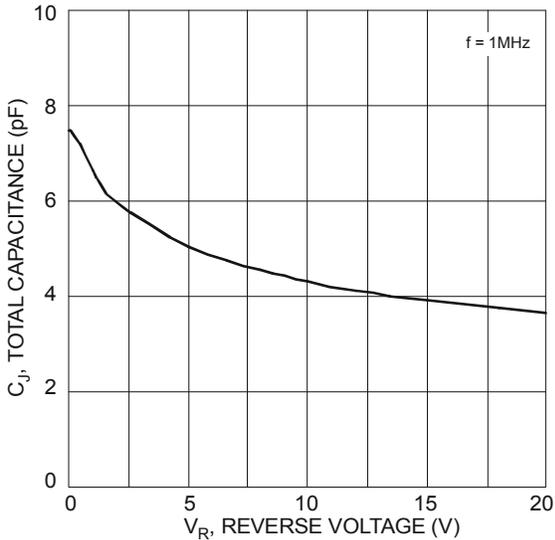


Figure 5 Typical Total Capacitance vs. Reverse Voltage

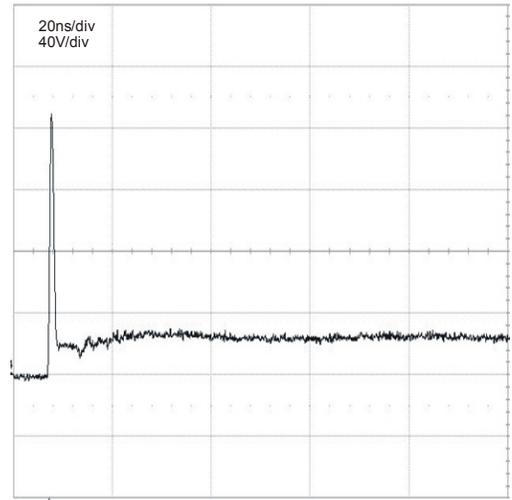


Figure 6 ESD Response to IEC 6100-4-2 (+8kV Contact Discharge)

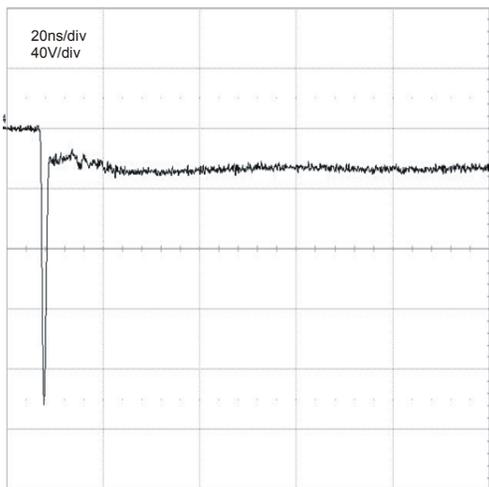


Figure 7 ESD Response to IEC 6100-4-2 (-8kV Contact Discharge)

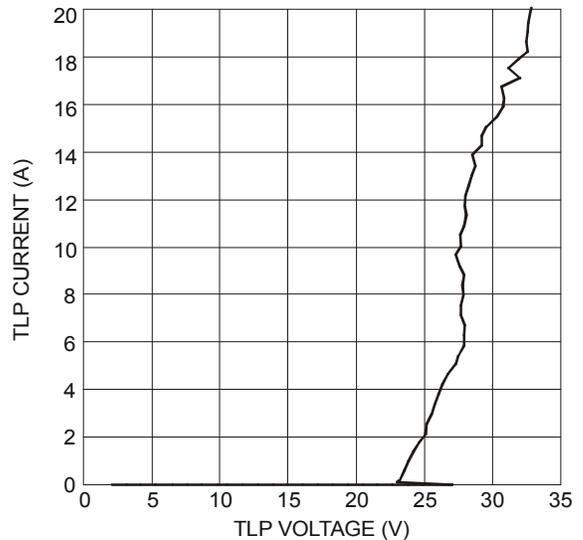
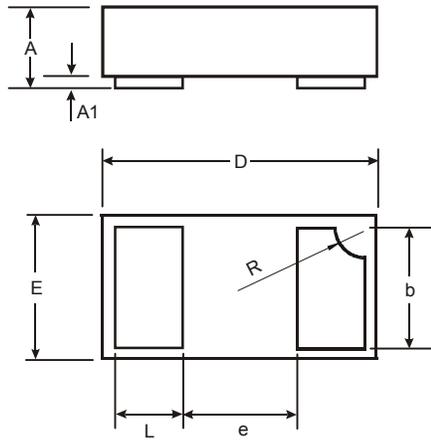


Figure 8 Transmission Line Pulsing (TLP) Current vs. Voltage

Package Outline Dimensions

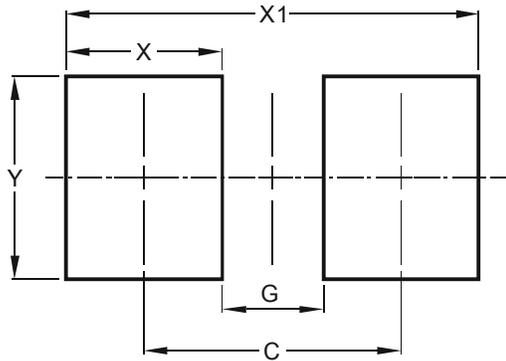
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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